

Title (en)
LIQUID-PHASE DIFFUSION BONDING ALLOY FOIL FOR HEAT-RESISTANT MATERIAL WHICH IS JOINABLE IN OXIDIZING ATMOSPHERE

Title (de)
FLÜSSIG-PHASENDIFFUSIONSGEBUNDENE LEGIERUNGSFOLIE FÜR WÄRMEBESTÄNDIGES MATERIAL DAS IN OXIDIERUNG VERBINBAR IST

Title (fr)
FEUILLE D'ALLIAGE DE SOUDURE PAR DIFFUSION EN PHASE LIQUIDE POUR MATERIAU RESISTANT A LA CHALEUR POUVANT ETRE SOUDE EN ATMOSPHERE OXYDANTE

Publication
EP 0757111 A1 19970205 (EN)

Application
EP 95913372 A 19950329

Priority
• JP 9500594 W 19950329
• JP 5940694 A 19940329

Abstract (en)
Alloy foils for liquid-phase diffusion bonding of heat-resisting metals in an oxidizing atmosphere comprise 6.0 to 15.0 percent silicon, 0.1 to 2.0 percent manganese, 0.50 to 30.0 percent chromium, 0.10 to 5.0 percent molybdenum, 0.50 to 10.0 percent vanadium, 0.02 to 1.0 percent niobium, 0.10 to 5.0 percent tungsten, 0.01 to 0.5 percent nitrogen, 0.10 to 5.0 percent boron, plus 0.005 to 1.0 percent carbon, and/or either or both of 0.01 to 5.0 percent titanium and 0.01 to 5.0 percent zirconium, all by mass, with the balance comprising nickel and impurities, and have a thickness of 3.0 to 300 μ m. Alloy foils for liquid-phase diffusion bonding of heat-resisting metals in an oxidizing atmosphere are also available with substantially vitreous structures. <IMAGE>

IPC 1-7
C22C 19/05

IPC 8 full level
B23K 20/00 (2006.01); **B23K 35/02** (2006.01); **B23K 35/30** (2006.01); **C22C 19/05** (2006.01)

CPC (source: EP KR US)
B23K 35/0233 (2013.01 - EP US); **B23K 35/3033** (2013.01 - EP US); **B23K 35/304** (2013.01 - EP US); **C22C 19/05** (2013.01 - KR); **Y10T 428/12431** (2015.01 - EP US); **Y10T 428/12937** (2015.01 - EP US); **Y10T 428/12944** (2015.01 - EP US)

Cited by
AU2002214472B2; US6303015B1; WO0238327A1; WO0131085A3; US7285151B2; US9513071B2; US9513072B2; US9702641B2; US9919385B2; WO02090038A1; EP2666582B1

Designated contracting state (EPC)
DE FR GB

DOCDB simple family (publication)
WO 9526419 A1 19951005; CN 1144542 A 19970305; EP 0757111 A1 19970205; EP 0757111 A4 19970625; JP 2820613 B2 19981105; JP H07268521 A 19951017; KR 970702381 A 19970513; US 5759300 A 19980602

DOCDB simple family (application)
JP 9500594 W 19950329; CN 95192265 A 19950329; EP 95913372 A 19950329; JP 5940694 A 19940329; KR 19960705331 A 19960924; US 71631496 A 19960927